LoSa-V60-305

PRELIMINARY SPECIFICATIONS

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CONTENTS

1. Description (Features & Applications)	3/18
2. Outline Dimensions	4/18
3. Absolute Maximum Rating	5/18
4. Electrical-Optical Characteristics	5/18
5. Characteristics Diagram	6/18
6. Reliability Test Items and Conditions	11/18
7. Soldering Conditions	12/18
8. Packing	13/18
9. Precaution	14/18
10. Measurement Methods	17/18
11. Revision Sheet	18/18
Appendix A. Visual Identification & Electrode Map (Top View)	
Appendix B. Rationale for Bottom-Side Thermocouple [Tb(bottom)] Measurement	

Preliminary

1. Description

ELPHOTON's LoSa-V60-305 is a precision-engineered deep-UV LED package optimized for reliability and optical efficiency. With a peak wavelength of 305–310 nm and a narrow 60° viewing angle, the device delivers concentrated UV output for demanding applications. The package is built on an AlN substrate for excellent thermal management, enabling stable performance under continuous operation. LoSa-V60-305 is well suited for precision curing systems, water/air/surface treatment, sterilization, sensing, and spectroscopy where uniformity and durability matter.

◆ Features

- Lighting Color(Peak Wavelength): 305-310 nm
- Surface Mount Type LED Package: 3.65 × 3.65 × 2.70 (L × W × H) [Unit: mm]
- View angle (2Θ1/2=60°)
- RoHS compliant; Pb-free
- ESD Protection up to 2KV
- Pb-free reflow compatible (details in "Soldering Conditions")

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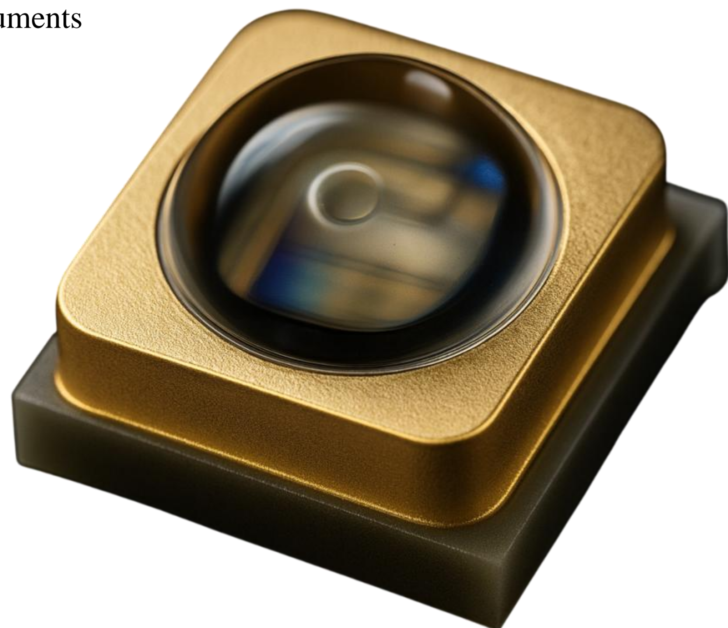
◆ Applications

- Precision curing systems; water/air/surface disinfection and sterilization
- Fluorescence spectroscopy
- Sensor light / UV sensing
- Medical spectroscopy and analytical instruments

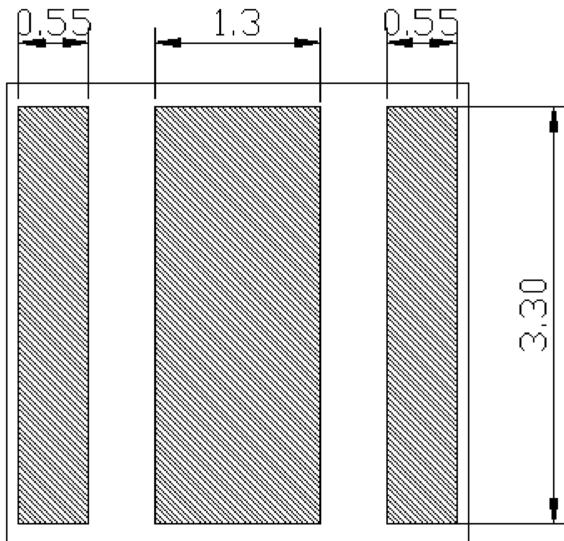


2. Outline Dimensions

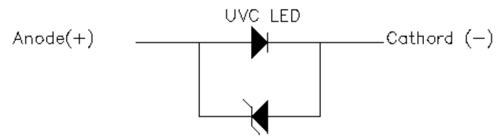
Anode (+) Cathode (-)

3.65 3.65 3.30 2.30 1.30 3.30 2.72

Recommend Solder Pattern



Electrical Scheme of SMD



* Note

1. All dimensions are in millimeters.
2. Undefined tolerance is $\pm$0.1mm
3. ESD protection

3. Absolute Maximum Rating at Ta = 25℃

Parameter	Symbol	Value			Unit
		Min.	Typ.	Max	
Forward Current	I_F	-	-	500	mA
Power Dissipation	P_D	-	-	3.1	W
Operating Temperature	T_{OPR}	-40	-	+75	℃
Storage Temperature	T_{STG}	-40	-	+100	℃
Junction Temperature	T_j	-	-	90	℃

4. Electro-Optical Characteristics at Ta = 25℃

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Parameter	Conditions	Symbol	Min.	Typ.	Max	Unit
Peak Wavelength	I_F=350mA	W_p	305	-	310	nm
Radiant Flux		ϕe	110	-	160	mW
Forward Voltage		VF	4.5	-	6.0	V
Spectrum Half Width		Δλ	-	13	-	nm
View Angle		2θ½	-	60	-	°
Thermal Resistance, Junction – PCB bottom		$Rth_{j\text{-}b}$	-	5.9	-	℃/W

Note
* These values measured by Optical spectrum analyzer and integrating sphere measuring system. And tolerances are followings as below.
* Rth j-b is the thermal resistance from chip junction to PCB bottom
* Reference for thermal resistance: Using 2.5x2.5x1.6cm aluminum MCPCB

1. Peak Wavelength Tolerance ± 3.5nm
2. Radiant Flux Measurement tolerance ±10%
3. Forward Voltage Tolerance ± 3%
4. All characteristics are measured by Elphoton

5. Characteristics Diagrams at Ta=25°C

FIG 1. Forward Current vs. Forward Voltage

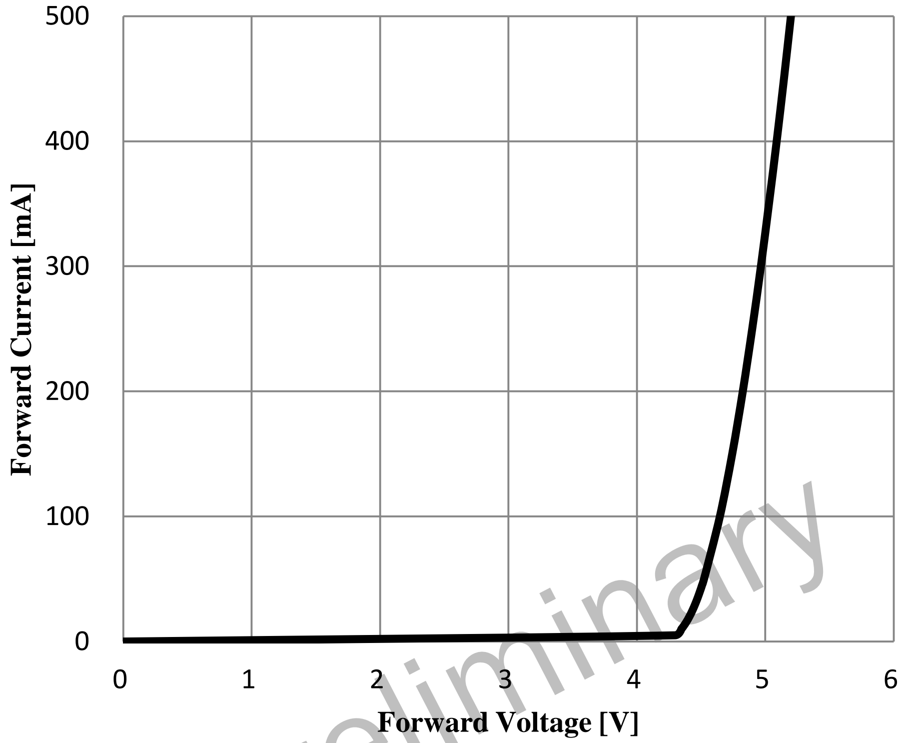

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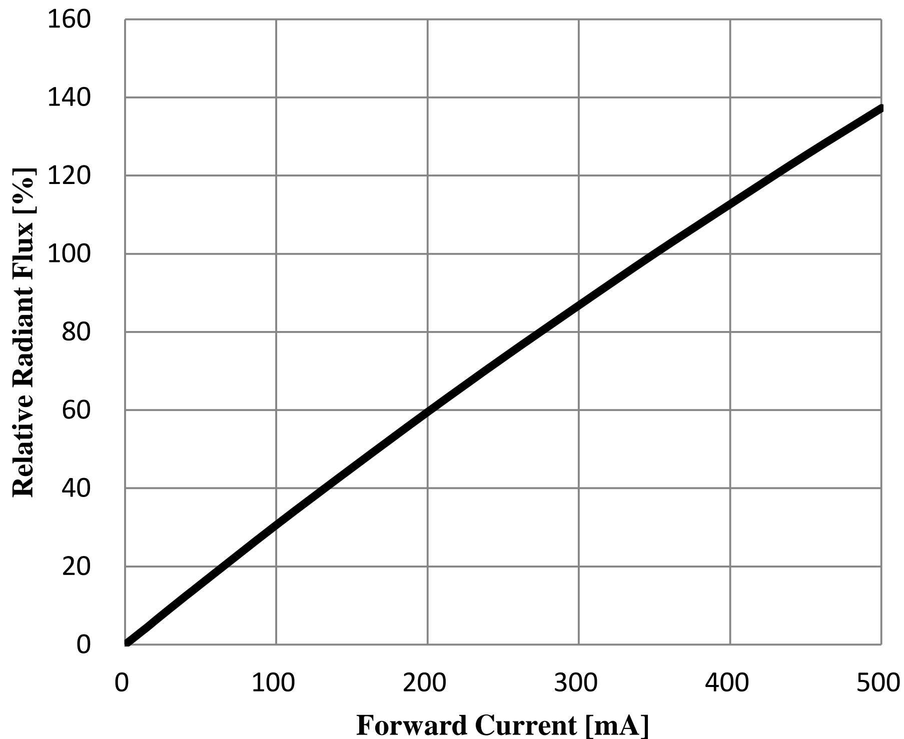
FIG 2. Relative Radiant Flux vs. Forward Current



5. Characteristics Diagrams at Ta=25°C, IF=350mA

FIG 3. Relative Peak Wavelength vs. Forward Current

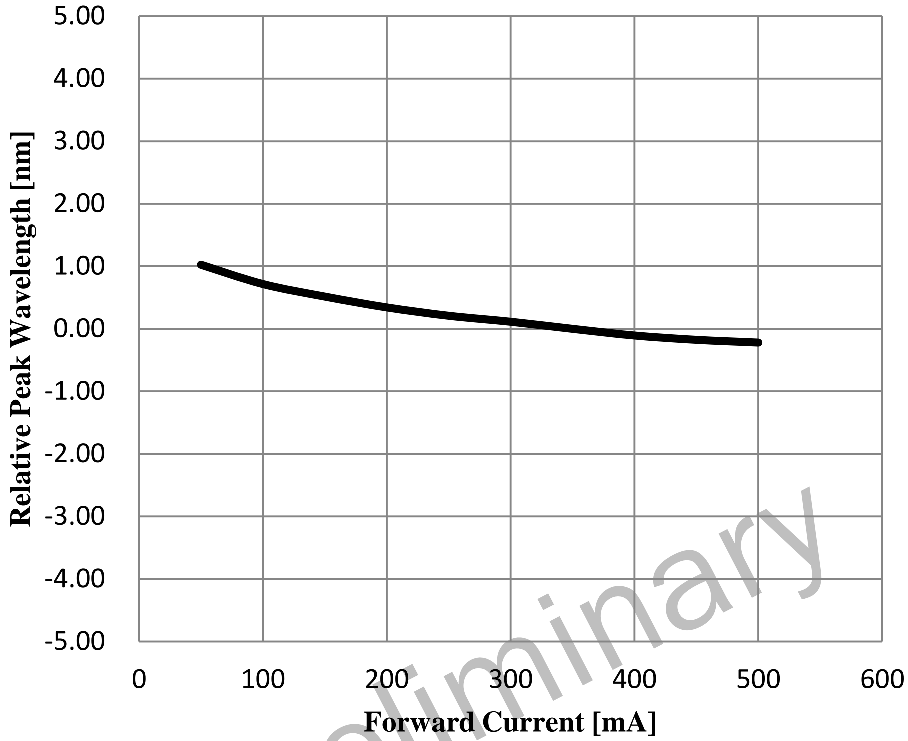


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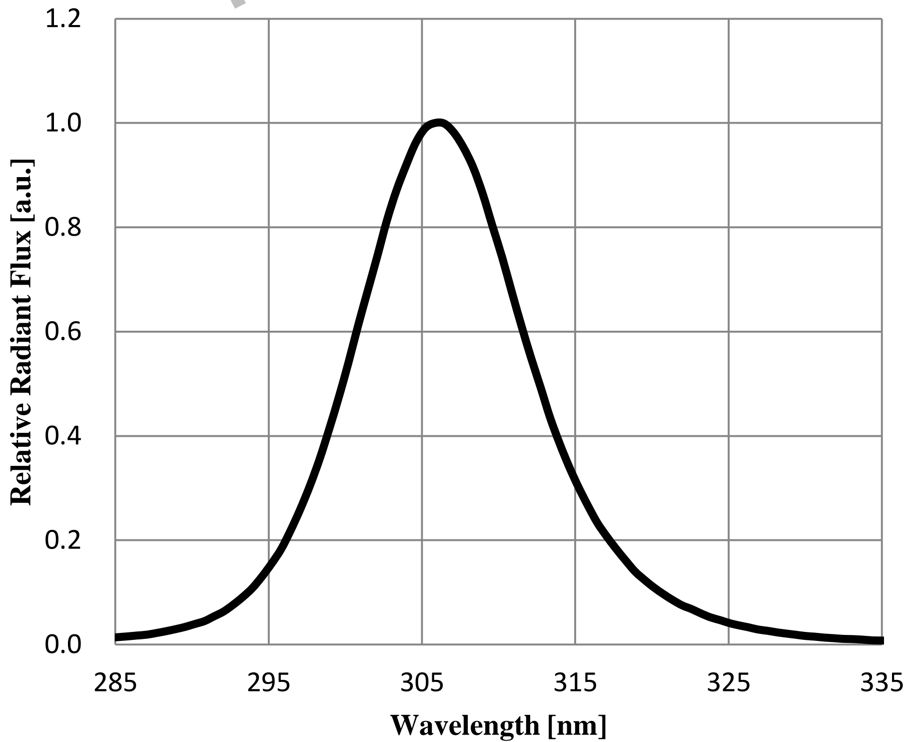
FIG 4. Spectrum



5. Characteristics Diagrams at IF=350mA

FIG 5. Relative Forward Voltage vs Ambient Temperature

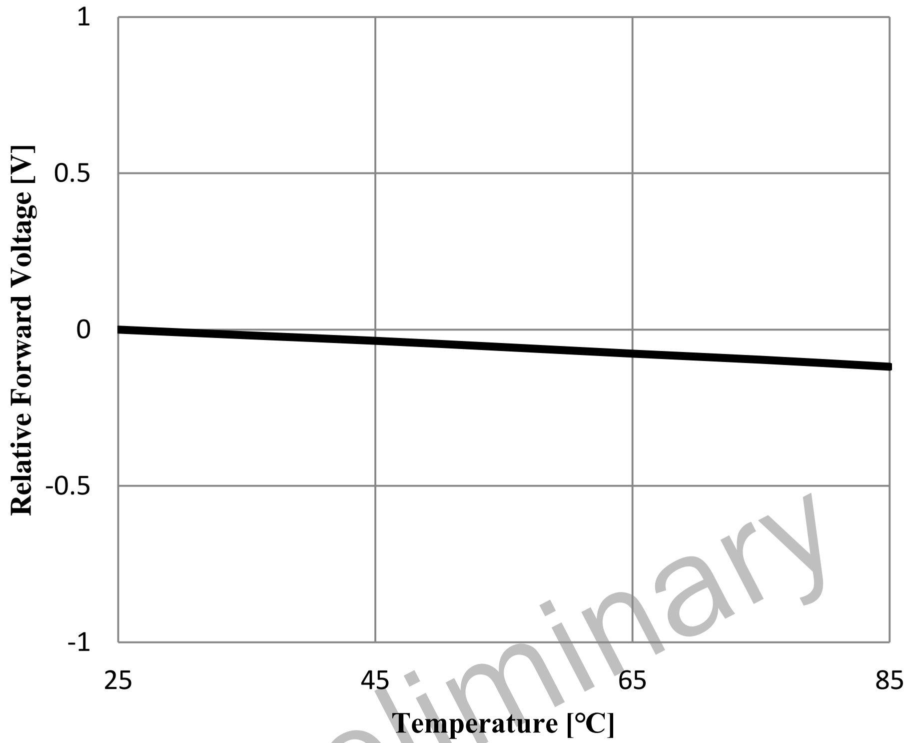


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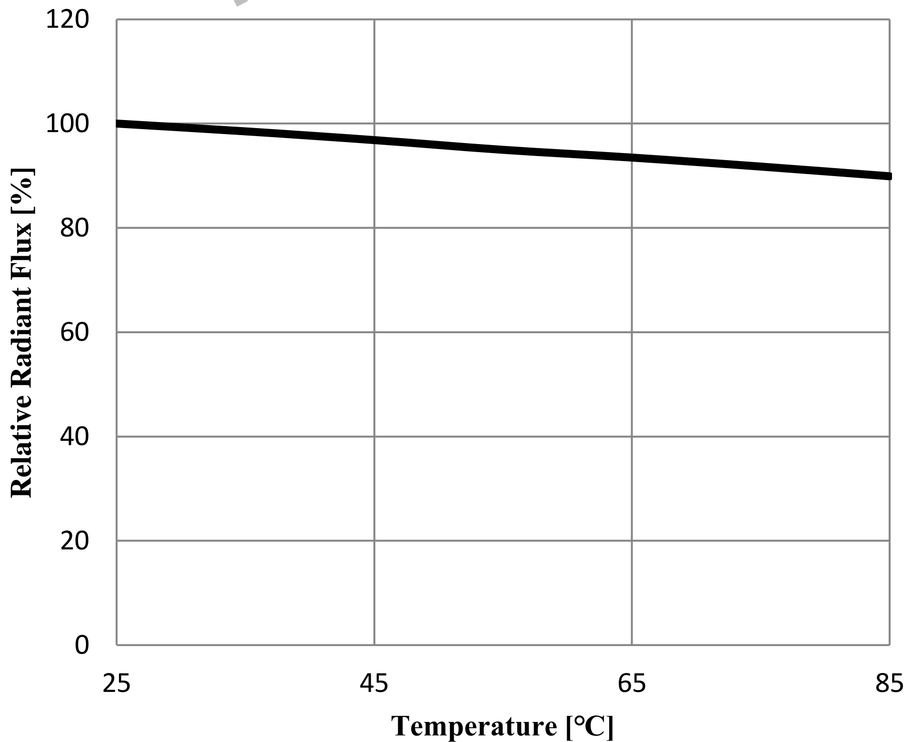
FIG 6. Relative Radiant Flux vs Ambient Temperature



5. Characteristics Diagrams at Ta=25°C, IF=350mA

FIG 7. Relative Peak Wavelength vs. Temperature

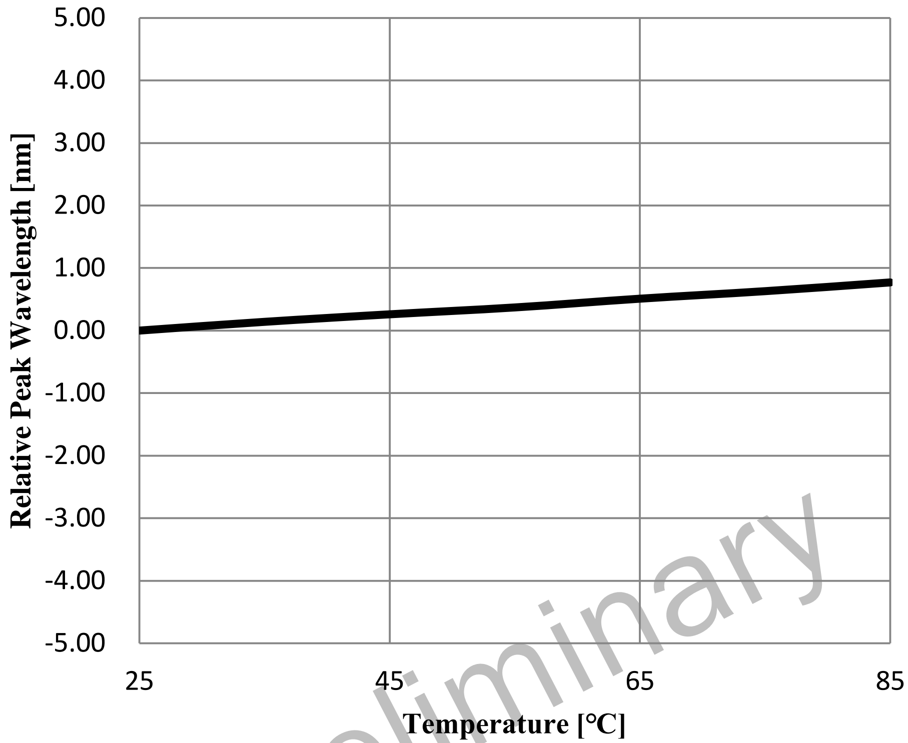


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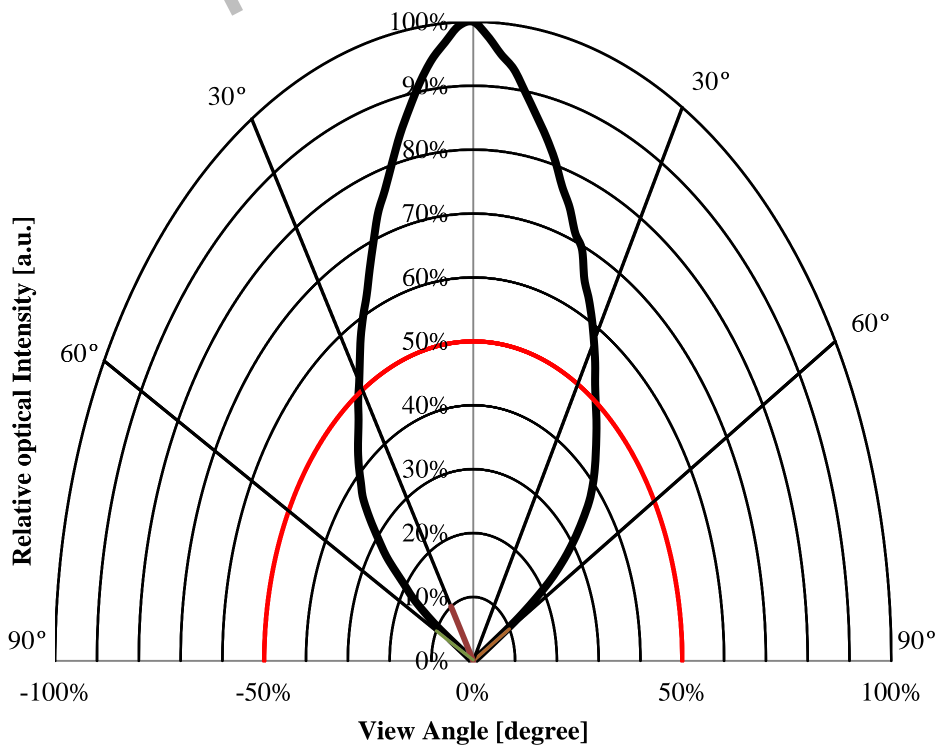
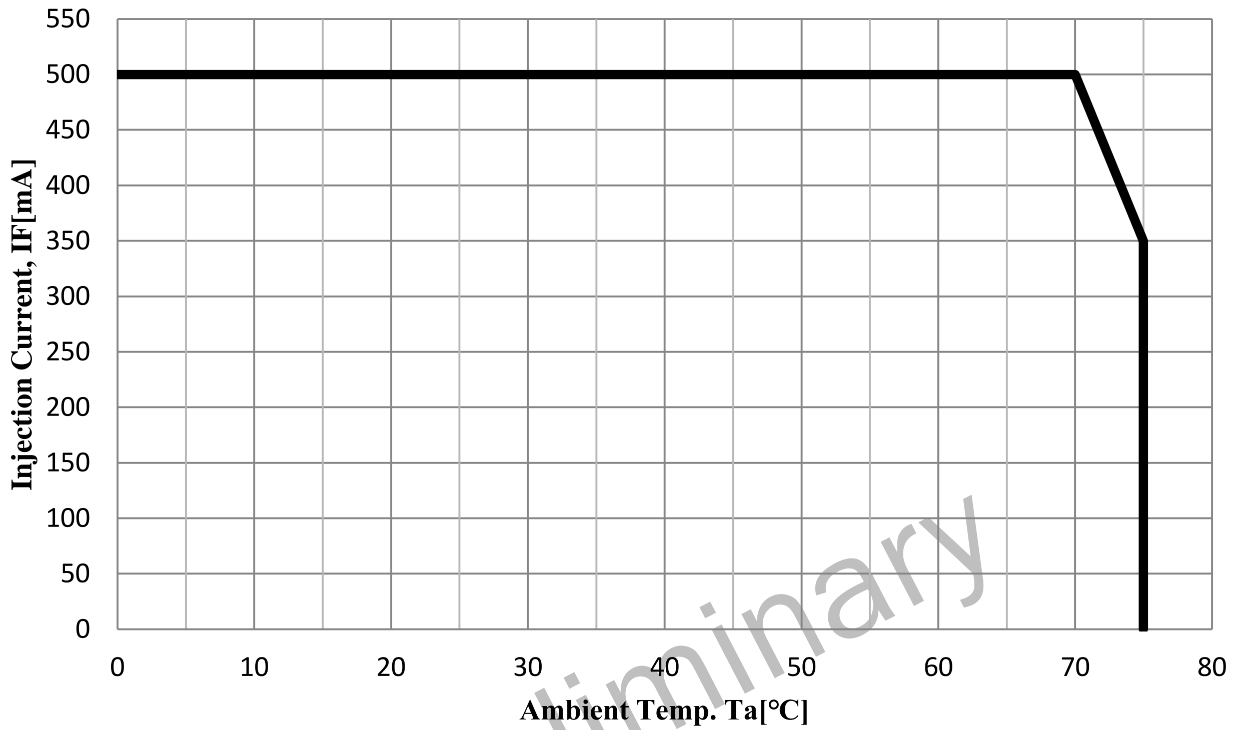
FIG 8. Far-field Emission Pattern



5. Characteristics Diagrams at Rth_j-b = 5.9°C/W

FIG 9. Derating



Note

- Rth j-b is the thermal resistance from chip junction to PCB bottom
- Reference for thermal resistance: Using 2.5x2.5x1.6cm aluminum MCPCB
- The derating curve is defined so that the junction temperature does not exceed 90 °C at any ambient condition.

6. Reliability Test Items and Conditions

1) Criteria for Judging the Damage

Parameter	Symbol	Condition	Criteria for Judgement	
			Min.	Max.
Forward Voltage	VF	IF=350mA	-	Initial value*1.1
Radiant Flux	ϕe	IF=350mA	Initial value*0.5	-

2) Reliability Tests

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Test Item	Test Conditions	Test Time	Sample Q'ty
Room Temperature Operating Life [RTOL]	Ta=25°C, If=350mA	1000hrs	6 pcs
High Temperature Operating Life [HTOL]	Ta=75°C, If=350mA	1000hrs	6 pcs
High Temperature Storage Life [HTSL]	Ta=100°C	1000hrs	6 pcs
Low Temperature Storage Life [LTSL]	Ta=-40°C	1000hrs	6 pcs
ESD	HBM, Voltage =2kV R=1.5kΩ, C=100pF	3 times Positive / negative	6 pcs

Note
- Using 2.5×2.5×1.6cm Aluminum MCPCB.
- 3ea of MCPCBs are mounted on 15×5×2.8cm metal thermal heat sink when reliability test.
- Measurements are performed after allowing the LEDs to return to room temperature.

7. Soldering Conditions : Convection Reflow

1) Solder paste / stencil

- Use Pb-free SnAgCu (SAC) solder paste (e.g., SAC305 or equivalent).
- Recommended stencil thickness: 60–80 µm.
- Recommended stencil aperture area ratio: 60–80%.
- Refer to “Mask Solder Pattern” on page 4.

2) Reflow profile (Pb-free, SAC)

- Ramp-up rate: ≤ 3 °C/s
- Pre-heating (soak) temperature: 150–200 °C
- Pre-heating time: ≤ 150 s
- Peak temperature: 260 °C max
- Time within 5 °C of peak: ≤ 30 s
- Cool-down rate: ≤ 6 °C/s (avoid rapid thermal shock)

3) Process notes

- Maximum number of reflow cycles: 2 (double-sided assembly allowed within this limit).
- Avoid rapid cooling after peak temperature. Extending the pre-heating (soak) time can help minimize lens/window distortion.
- Do not apply wave soldering or direct heating to the package body.
- Actual profiles may require optimization depending on board design, copper density, and oven capability.

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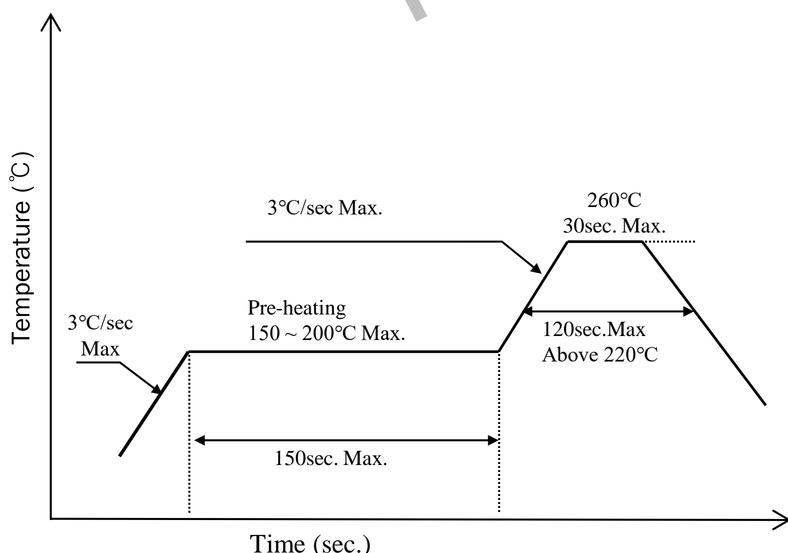


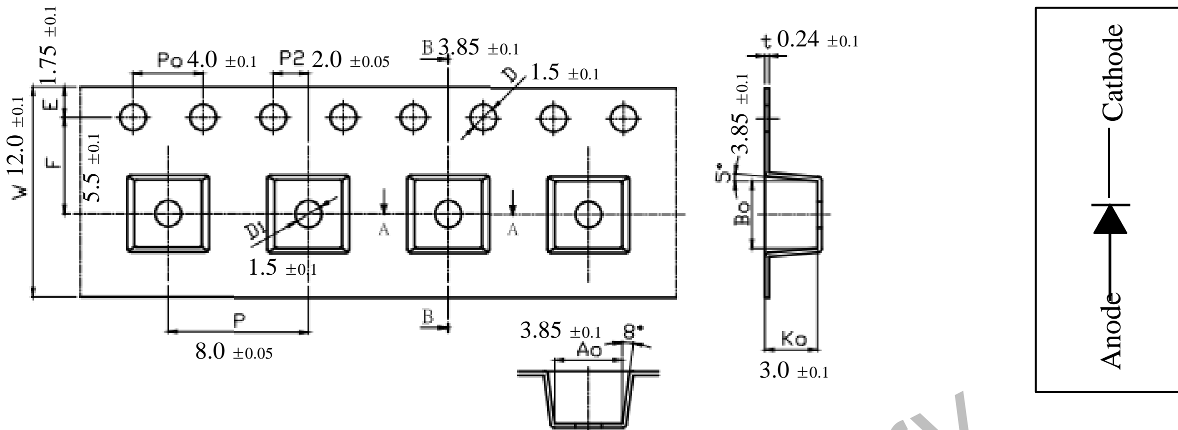
Reflow Soldering	
	Pb-free(SnAgCu)
Pre-Heating	150 ~ 200°C
Pre-Heat Time	150sec. Max.
Peak Temperature	260°C Max.
Time within 5°C at Peak Temperature	30sec. Max.

Note
- Reflow soldering may be performed up to 2 cycles.
- Peak temperature is 260 °C max.
- Profile must be optimized per board/oven; avoid rapid thermal shock.

8. Packing

1) Tape & Reel Dimensions (unit : mm)

- Tape



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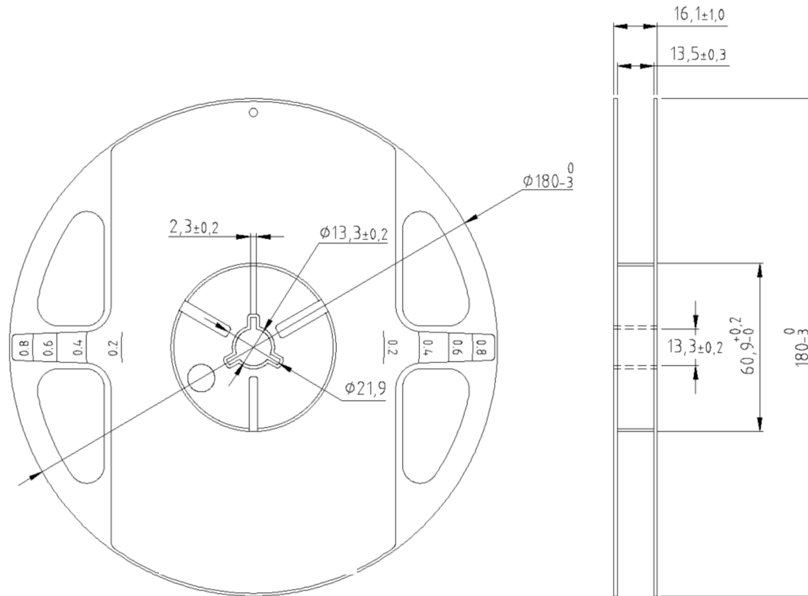
- Reel



Note
- Maximum quantity : 1,000pcs/7inch reel (Minimum quantity: 100pcs)
- Carrier Tape Front Blank Space : 180mm (Min) , Rear Blank Space : 360mm (Min)
- Adhesion strength of cover tape is 0.1 ~ 0.7N when the cover tape is turned off from the carrier tape.
- The maximum number of consecutive missing lamps is two

9. Precaution

1) Cleaning

- Do not immerse the device in liquids (water, oil, organic solvents).
- If cleaning is required, use IPA (>99%) with a lint-free swab locally around the package; do not rub the quartz dome. Finish with dry N_2 blow.
- Ultrasonic cleaning is prohibited.
- Strong acids/alkalis, chlorinated solvents, silicone oils, and abrasive wipes are not allowed.
- Verify the chosen cleaning method with sample qualification before mass production.

2) Pick-and-Place / Mounting & Reflow

- Top pick on the dome lens is allowed only with compliant tooling:
  - Use a ring-type or concave vacuum nozzle that matches the dome curvature and spreads the load away from the center.
  - If a flat nozzle must be used, add soft/compliant padding, keep contact time minimal, and avoid any lateral sliding/rotation.
  - Where equipment allows, side-grip or frame/sidewall support is preferred.
- Ensure adequate tool/fixture clearance around the dome and confirm with a first-article run to prevent collisions.
- Pb-free reflow: peak ≤ 260 °C, ≤ 2 cycles. Avoid rapid thermal shock. Handle/test only after the board returns to room temperature.
- Electrical: Reverse voltage is not allowed. Use a constant-current driver with soft-start and over-current/transient protection.

Preliminary

3) Moisture & Storage (No formal MSL assigned)

- Shipped in a moisture-barrier bag (MBB) with silica.
- Store sealed in the original MBB at 5–30 °C in a dry, controlled environment (typically ≤60 % RH). No shelf-life or exposure time is specified at this stage.
- If the bag seal is compromised, exposure time/humidity is unknown or prolonged, perform a dry-out at 60 °C for 2 hours before reflow.
- Packaging caution: Confirm reel/carrier and cover-tape heat tolerance with your supplier. If not heat-rated, transfer devices to a heat-stable tray/tape for dry-out, or use a dry cabinet (<10 % RH) for 24–48 hours.
- Reseal opened reels in MBB with fresh desiccant for storage.

9. Precaution

4) Handling / ESD–EOS

- Handle only at ESD-protected workstations (wrist strap, grounded floors/tools, ionizer).
- Prevent surge, static discharge, reverse voltage, and current spikes.
- Use a constant-current driver with proper protection features.

5) Manual Handling

- Do not touch the lens with fingers. Oils/particles reduce optical output.
- Grip the metal frame or package sidewalls. Use PTFE-tipped tweezers or ESD vacuum tweezers.
- Use guards/fixtures to avoid contact with the dome during assembly.

6) Rework

- Limit local rework; excessive hot-air exposure can damage the dome or bond line.
- After device removal, clean pads with low-activity flux + IPA; no ultrasonic cleaning.

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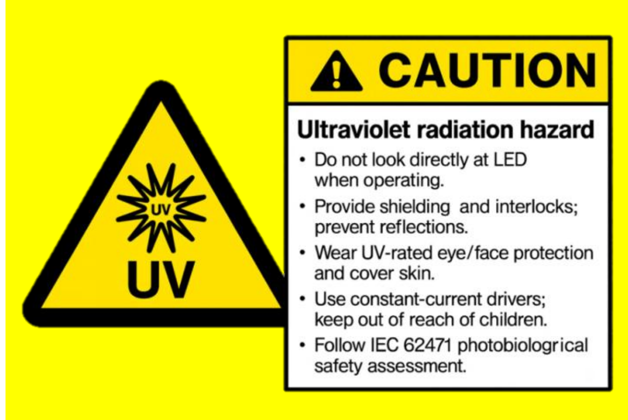
7) Chemical Compatibility

- Allowed: IPA, dry N_2 blow.
- Not allowed / not recommended: Acetone/MEK, chlorinated solvents, strong acids/alkalis, silicone oils (release agents/coatings), abrasive wipes.
- If conformal coating is used, mask the lens to avoid UV transmission loss.

9. Precaution



8) Optical Safety (UV)

- Ultraviolet radiation (≈200–400 nm: UV-C/UV-B/near-UV) can be hazardous to eyes and skin.
- Do not look directly at the LED when operating.
- Provide optical shielding and interlocks; prevent reflections.
- Wear UV-rated eye/face protection and cover skin during testing.
- Drive with constant-current only; follow thermal/ESD precautions.
- Keep out of reach of children and untrained personnel.

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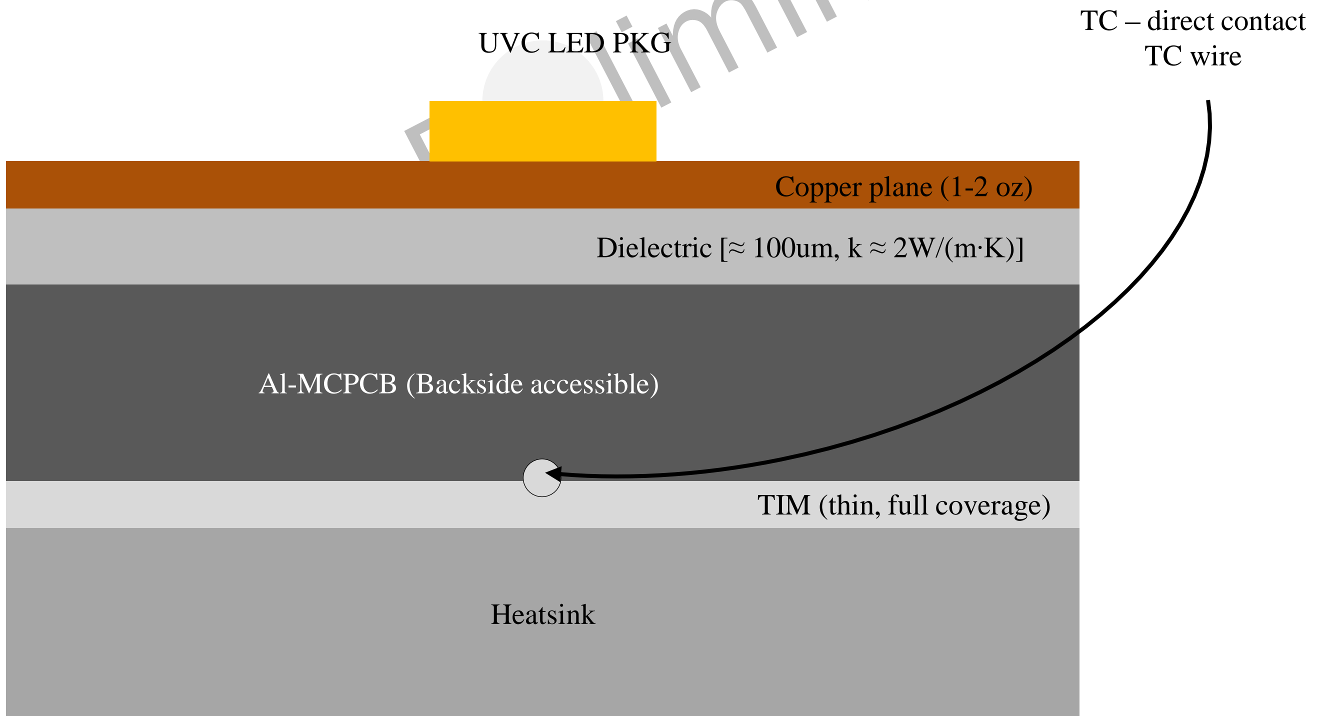
10. Measurement Methods

1) Tb(bottom) Measurement Guideline

- Attach a K-type TC to the MCPCB backside (aluminum base) under the LED optical center.
- Prepare a bare-metal spot Ø 1.5–2.0 mm; clean with IPA.
- Fix with a very thin layer of thermally conductive adhesive; cover with one layer of Kapton.
- Do not place the bead between MCPCB and heatsink. If required, provide a relief groove so the bead sits flush while keeping full TIM contact.
- Define Tb(bottom) after ≥30 min stabilization at the target drive; typical uncertainty ±1–2 °C.
- Junction estimate:

$$T_j = T_{b(bottom)} + R_{th(j-b)} \times P_{out}\ , \qquad P_{out} \approx I_F \times V_F$$



Do not place the TC bead between MCPCB and heatsink (keeps full TIM contact).

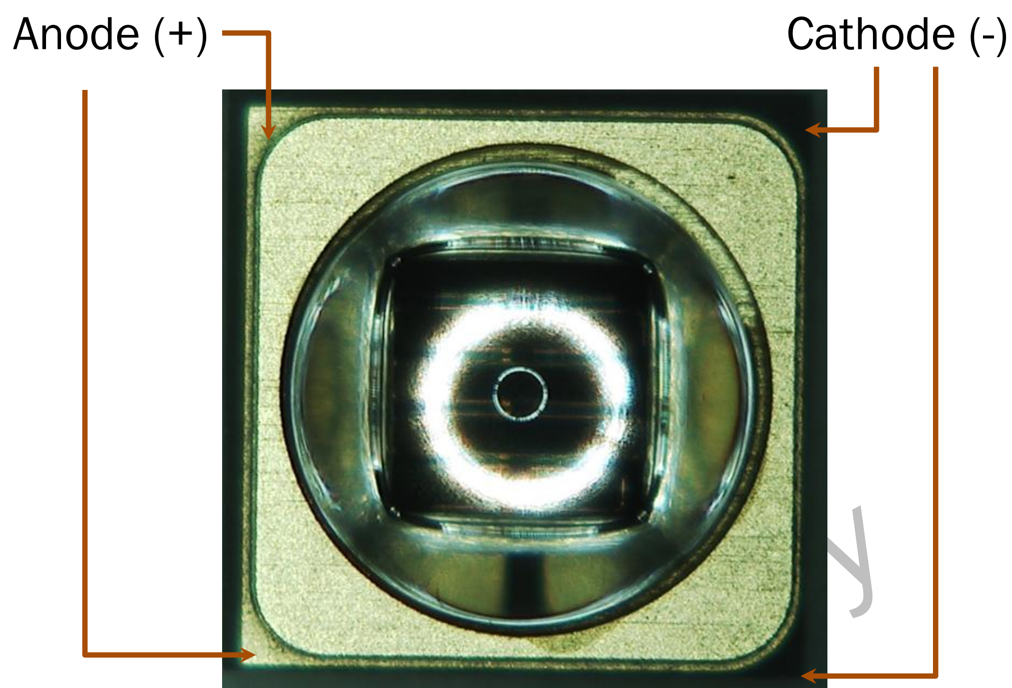
> Note — Rationale (summary).
> - Backside probing reduces design/process sensitivity compared to top-pad probing, aligns with the thermal path Rth(j-b), and lowers handling/ESD risk.
> - It yields more reproducible, model-consistent temperatures for specification and compliance. (See Appendix B for details.)

11. Revision Sheet

Revision	Date	Page	Description	Remark
Rev.1.0	25.09.22	-	Preliminary edition	

Appendix A.
Visual Identification & Electrode Map (Top View)

Top View Photo (Actual Device)



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Appendix B.
Rationale for Bottom-Side Thermocouple [Tb(bottom)] Measurement

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Rationale for Bottom-Side Thermocouple [Tb(bottom)] Measurement

We specify Tb(bottom) by attaching a fine-wire thermocouple to the MCPCB backside (aluminum base), directly under the LED center, rather than probing any top-side pads. This approach is chosen for the following reasons:

- Better repeatability across designs. Top-side readings depend on local pad geometry, solder volume, mask openings, and nearby copper pours; these vary by customer PCB and process. Backside aluminum contact reduces design/process sensitivity, improving reproducibility between builds and sites.
- Direct correlation to the thermal model. The junction-to-backside thermal path is characterized as Rth(j-b). Measuring at the aluminum base provides a consistent boundary condition for estimating junction temperature:

$$T_j = T_{b(bottom)} + R_{th(j-b)} \times P_{out}\,, \qquad P_{out} \approx I_F \times V_F$$

- Lower measurement bias and handling risk. Avoids touching functional electrodes or adding solder/adhesive near the package that may alter heat spreading or introduce ESD/handling risks.
- Simple fixturing in real systems. A small relief groove/pocket in the heatsink allows the bead to sit flush on the aluminum base while maintaining full TIM contact, avoiding air gaps and preserving normal thermal performance.

Preliminary

Implementation notes.

Place a K-type TC on a clean, bare-metal spot (Ø 1.5–2.0 mm) on the MCPCB backside under the optical center. Fix with a very thin layer of thermally conductive adhesive and cover with one layer of Kapton to suppress convection. Do not place the bead between MCPCB and heatsink. Define Tb(bottom) after ≥ 30 min stabilization at the target drive; typical uncertainty ±1–2 °C (dominant factors: adhesive thickness, ambient airflow).

Trade-offs.

Backside readings have a slightly longer time constant than top-side pad measurements; however, once stabilized they provide a more transferable and model-consistent temperature for specification and compliance. Top-side probing may still be used for engineering debug, but it is not the compliance reference for this product.